

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3278	((ball adj grid adj array) or BGA) and substrate and chip and adhesive and insulat\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/02 10:46
L2	2265	1 and thermal	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/02 10:46
L3	2075	2 and wir\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/02 10:47
L4	65	3 and ((die adj bonding) with layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/02 11:14
L5	0	1 and (((chip or die) adj bonding) with adhesive)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/02 11:15
L6	180	1 and (((chip or die) adj bonding) with adhesive)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/02 11:34
L7	62	6 and bonding.ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/02 11:34
L8	3	("4933030" "5391604" "6175152").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/02 12:13
L9	0	("6552421").URPN.	USPAT	OR	ON	2005/09/02 13:00
L10	1471	257/787.ccls.	USPAT	OR	ON	2005/09/02 13:29
L11	1087	257/678.ccls.	USPAT	OR	ON	2005/09/02 14:09
L12	1111	257/777.ccls.	USPAT	OR	ON	2005/09/02 14:09